

ELEP HOLDER

## ELP NBD-5172K

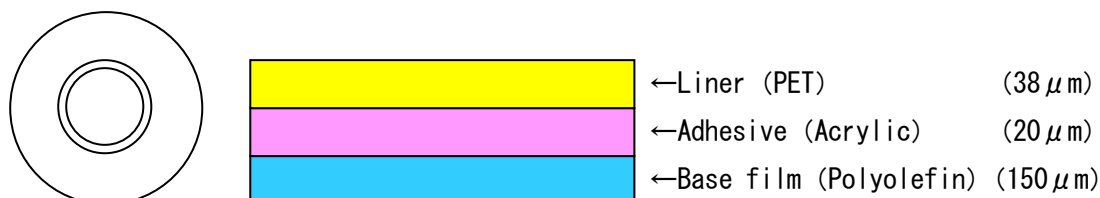
### Features

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- For package dicing process
- Expand type

### Structure

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### Properties

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Table.1 General properties

Item	Unit	ELP NBD-5172K
Color	–	Translucent
Total thickness	$\mu$ m	170
Adhesion on Si wafer before UV	N/20mm	9.0
Adhesion on Si wafer after UV		0.2

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ELP NBD-5172K-e 1/1  
26E-34163E-1309

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